Special Issue

Selected Material Related Papers from ICI2016

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Message from the Guest Editors

Dear Colleagues,

The aims and scope of the 2016 International Conference on Inventions is to make researchers focus on patent-based research. This Special Issue will also focus on inventions in materials engineering. Material-related invention is a solution to a specific technological problem and is an improvement on new processes, new materials, and new components, which also could achieve a completely unique function or radical breakthrough. We expect the conference to be a platform for successful patent inventors to share their experiences in inventing with all the participants of the conference.

Topics of the conference include:

- Patent-based inventions in materials engineering
- Inventions in device materials and sensors materials
- Inventions in processes for materials
- Inventions in biotechnology and materials

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